2SD1251A

Silicon NPN triple diffusion junction type

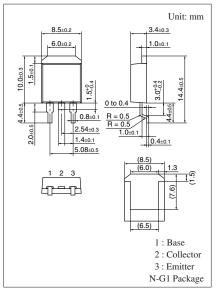
For power amplification

■ Features

- Wide safe operation area
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (En	V _{CBO}	80	V	
Collector-emitter voltage (V _{CEO}	80	V	
Emitter-base voltage (Coll	V _{EBO}	8	V	
Collector current	I_{C}	4	A	
Peak collector current	I_{CP}	6	A	
Base current	I_B	1	A	
Collector power dissipation		P _C	30	W
	$T_a = 25^{\circ}C$		1.3	
Junction temperature		T _j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C



Note) Self-supported type package is also prepared.

■ Electrical Characteristics $T_C = 25$ °C ± 3 °C

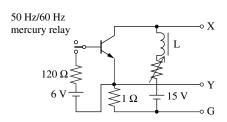
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_E = 0$			30	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 8 \text{ V}, I_{C} = 0$			1	mA
Collector-emitter sustaining voltage *2	V _{CEO(SUS)}	$I_C = 0.2 \text{ A}, L = 25 \text{ mH}$	80			V
Forward current transfer ratio	h _{FE1}	$V_{CE} = 3 \text{ V}, I_{C} = 0.1 \text{ A}$	40			_
	h _{FE2} *1	$V_{CE} = 3 \text{ V}, I_{C} = 1 \text{ A}$	30		160	
Base-emitter voltage	V_{BE}	$V_{CE} = 3 \text{ V}, I_{C} = 1 \text{ A}$			1.2	V
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 2 A, I_B = 0.4 A$			1.0	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.2 \text{ A}, f = 0.5 \text{ MHz}$		1		MHz

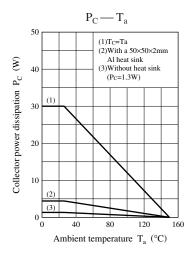
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

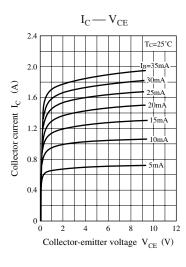
2. *1: Rank classification

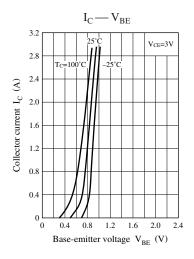
Rank	Q	Р	0
h _{FE2}	30 to 60	50 to 100	80 to 160

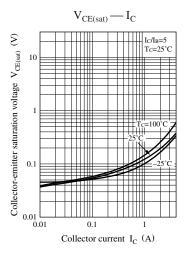
*2: $V_{CEO(SUS)}$ test circuit

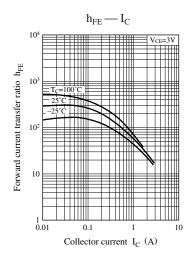


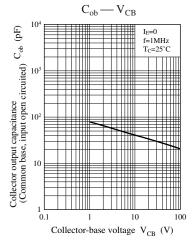


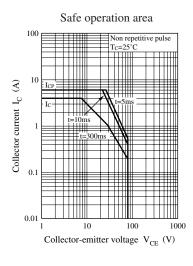


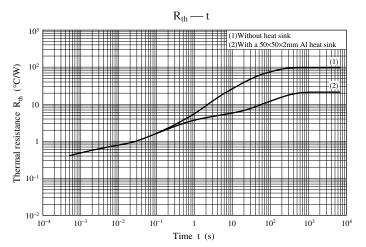












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